



# SOT2015-1

X2SON8, super thin small outline; no leads, 8 terminals, 0.35 mm pitch, 1.35 mm x 1 mm x 0.32 mm body

26 June 2019

Package information

## 1 Package summary

<b>Terminal position code</b>	B (bottom)
<b>Package type descriptive code</b>	X2SON8
<b>Package style descriptive code</b>	X2SON (super thin small outline; no leads)
<b>JEDEC package outline code</b>	MO-287
<b>Mounting method type</b>	S (surface mount)
<b>Issue date</b>	11-06-2019
<b>Manufacturer package code</b>	98ASA01419D

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	-	1.35	-	mm
package width	-	1	-	mm
seated height	-	0.32	-	mm
nominal pitch	-	0.35	-	mm
actual quantity of termination	-	8	-	



X2SON8, super thin small outline; no leads, 8 terminals, 0.35 mm pitch, 1.35 mm x 1 mm x 0.32 mm body

2 Package outline

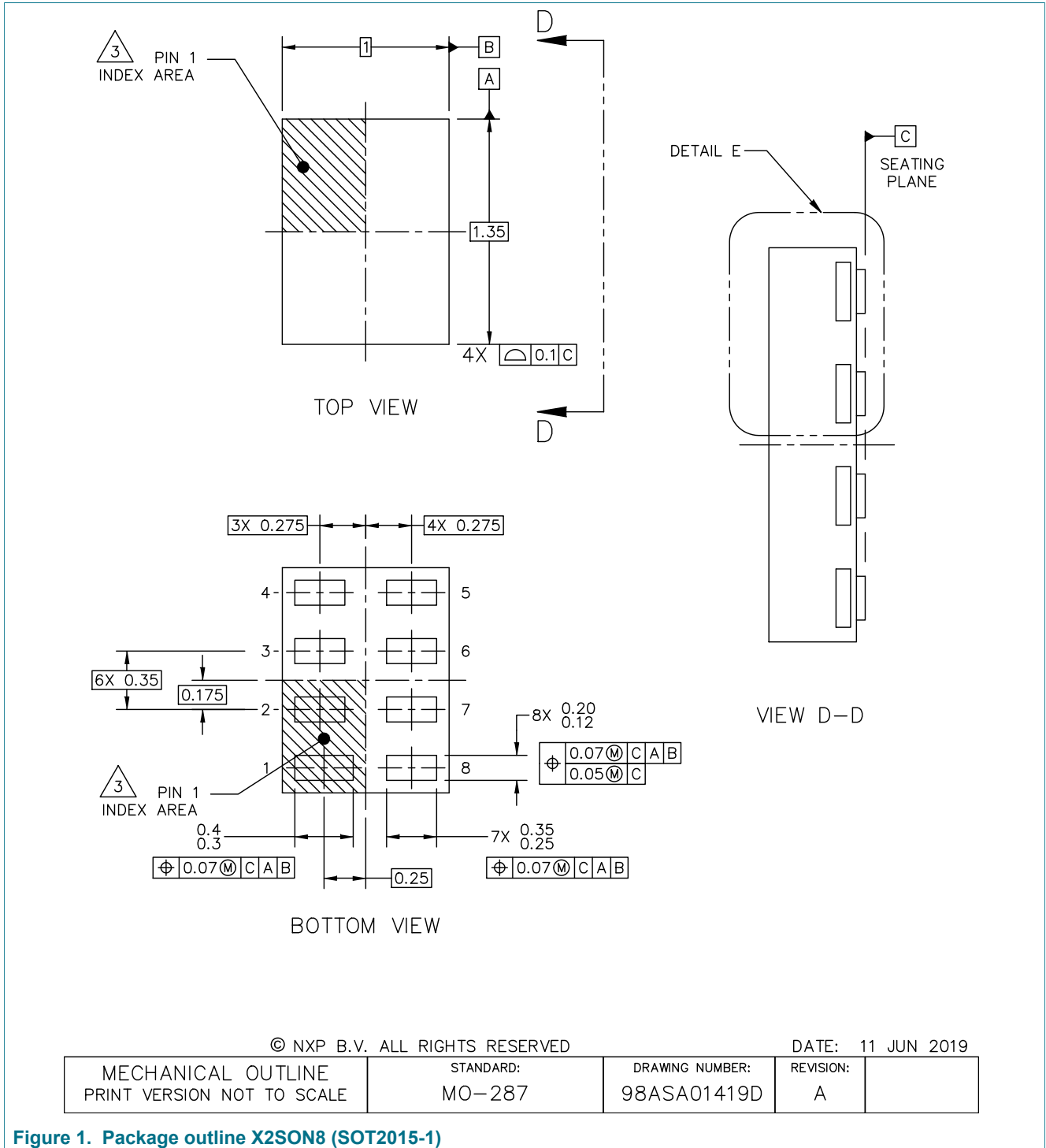
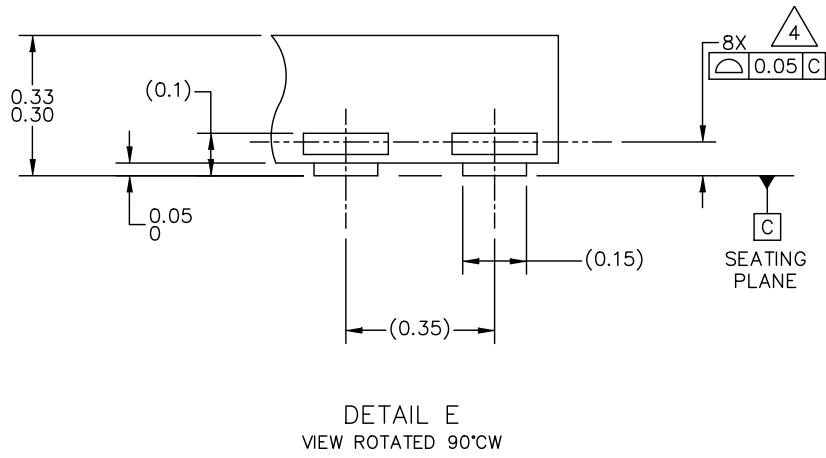


Figure 1. Package outline X2SON8 (SOT2015-1)

X2SON8, super thin small outline; no leads, 8 terminals, 0.35 mm pitch, 1.35 mm x 1 mm x 0.32 mm body



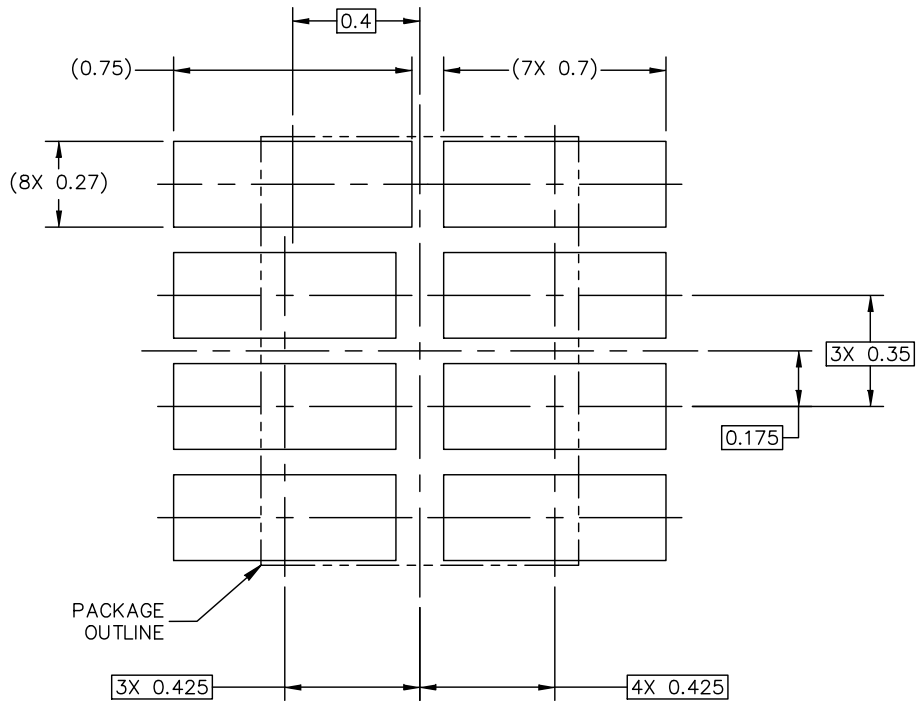
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DATE: 11 JUN 2019

MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: MO-287	DRAWING NUMBER: 98ASA01419D	REVISION: A	
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Figure 2. Package outline detail X2SON8 (SOT2015-1)

### 3 Soldering



#### PCB DESIGN GUIDELINES – SOLDER MASK OPENING PATTERN

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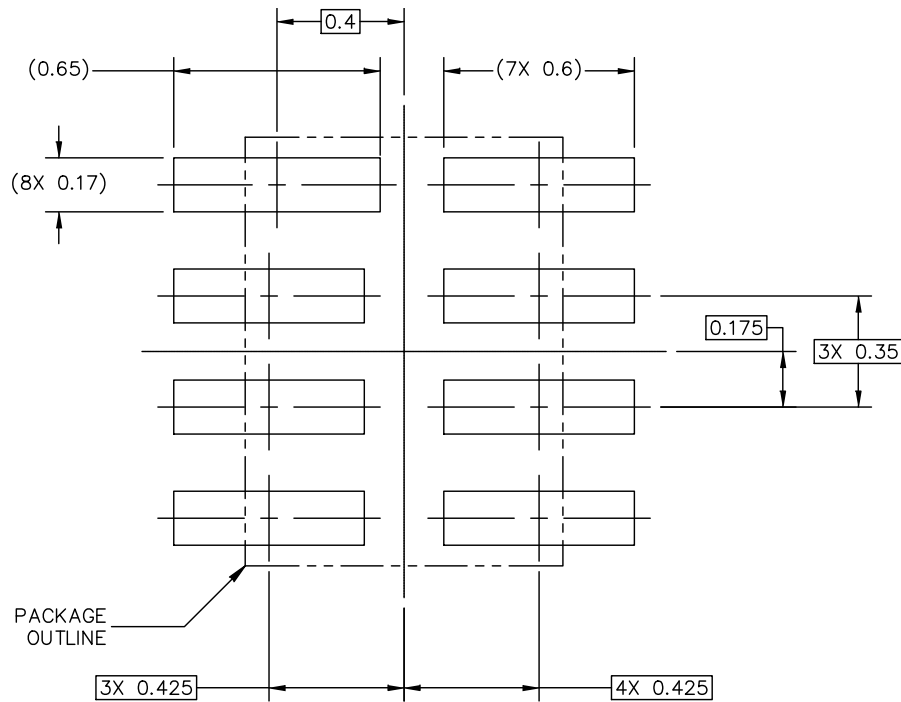
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Figure 3. Reflow soldering footprint part1 for X2SON8 (SOT2015-1)

X2SON8, super thin small outline; no leads, 8 terminals, 0.35 mm pitch, 1.35 mm x 1 mm x 0.32 mm body



PCB DESIGN GUIDELINES – I/O PADS AND SOLDERABLE AREA

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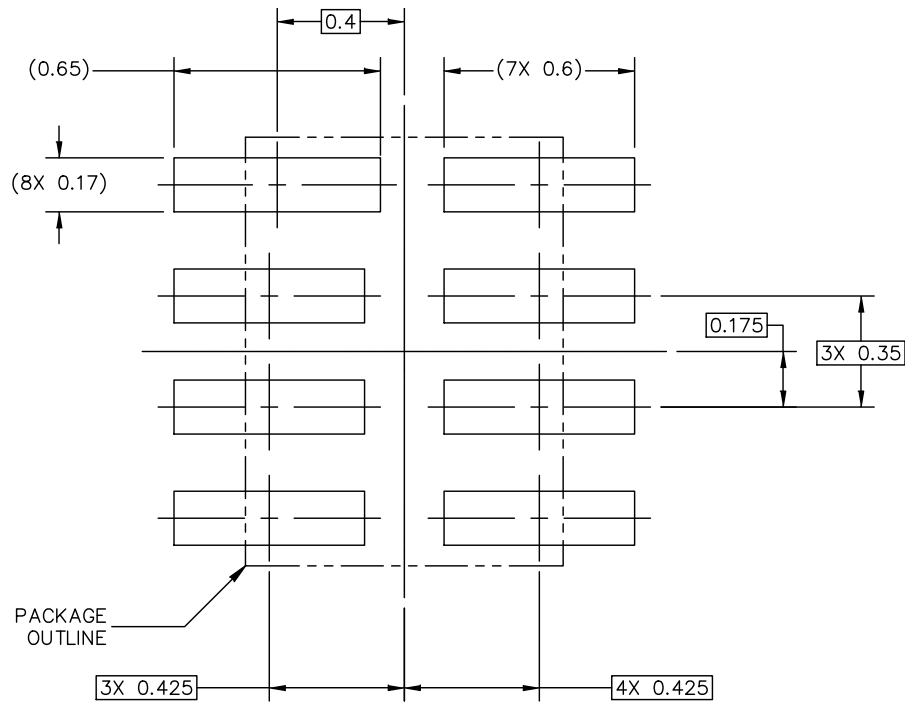
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Figure 4. Reflow soldering footprint part2 for X2SON8 (SOT2015-1)

X2SON8, super thin small outline; no leads, 8 terminals, 0.35 mm pitch, 1.35 mm x 1 mm x 0.32 mm body



RECOMMENDED STENCIL THICKNESS 0.1

PCB DESIGN GUIDELINES – SOLDER PASTE STENCIL

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Figure 5. Reflow soldering footprint part3 for X2SON8 (SOT2015-1)

X2SON8, super thin small outline; no leads, 8 terminals, 0.35 mm pitch, 1.35 mm x 1 mm x 0.32 mm body

NOTES:

1. ALL DIMENSIONS ARE IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. PIN 1 FEATURE SHAPE, SIZE AND LOCATION MAY VARY.
4. COPLANARITY APPLIES TO LEADS.
5. MIN METAL GAP SHOULD BE 0.15 MM.

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Figure 6. Package outline note X2SON8 (SOT2015-1)

## 4 Legal information

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